RECEIVED

NOV 1 9 2002

TC 1700

PATENT APPLICATION

00862.022294

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

n re Appliçation of:

DAISHĮ/SAIKI ET AI

Application No.: 09/897,014

Filed: July 3, 2001

MULTILAYERED STRUCTURE For:

RESIN MOLDED PRODUCT

AND METHOD OF MANUFACTURING

MULTILAYERED STRUCTURE

RESIN MOLDED PRODUCT

Examiner: R. Zacharia

Group Art Unit: 1773

November 15, 2002

Commissioner for Patents Washington, D.C. 20231

## SECOND INFORMATION DISCLOSURE STATEMENT

Sir:

In compliance with the duty of disclosure under 37 C.F.R. § 1.56 and in accordance with the practice under 37 C.F.R. §§ 1.97 and 1.98, the Examiner's attention is directed to the documents listed on the enclosed Form PTO-1449. Copies of the listed documents are also enclosed.

This Second Information Disclosure Statement is to submit documents cited in a European Search Report in a corresponding foreign application. A copy of the Search Report is enclosed.

The concise explanation of relevance for the non-English documents may be found, inter alia, in the enclosed European Search Report and/or in the included English abstract.

## STATEMENT UNDER 37 C.F.R. § 1.97(e)

Each item of information in this information disclosure statement was first cited in any communication from a foreign Patent Office in a counterpart foreign application not more than three months prior to the filing date of this Statement.

## **CONCLUSION**

It is respectfully requested that the above information be considered by the Examiner and that a copy of the enclosed Form PTO-1449 be returned indicating that such information has been considered.

Applicants' undersigned attorney may be reached in our New York office by telephone at (212) 218-2100. All correspondence should continue to be directed to our address given below.

Respectfully submitted,

rney for Applicants

Registration No. 48,512

FITZPATRICK, CELLA, HARPER & SCINTO 30 Rockefeller Plaza New York, New York 10112-3801

Facsimile: (212) 218-2200